Three International Conferences in One Place

- High Temperature Electronics
- Ceramic Interconnect and Ceramic Microsystems Technologies
- Thermal Management and Power Solutions

A technology crossover event!

April 28-30, 2020  •  Albuquerque, NM  •  Marriott Pyramid North

www.imaps.org/crossover
The forces behind the International Conferences on High Temperature Electronics (HiTEC), Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT), and Thermal Management & Power Solutions have joined for a special crossover technology extravaganza.

All three conferences will be held at the Marriott Pyramid North in Albuquerque, New Mexico from April 28-30, 2020. Each conference will sustain its own unique programming but share common networking and exhibitor functions.
KEY DATES AND LOCATION

Crossover Event Dates

April 27-30, 2020
- Conference Programs: April 28-30
- PDCs: April 27
- Exhibition: April 28-30

Crossover Event Location & Hotel

Marriott Pyramid North
5151 San Francisco Road NE
Albuquerque, New Mexico USA

How to Book Your Room:
- $129/night + taxes and fees
- Event discount rate ends on April 8th.

For reservations by web click here.
For reservations by phone call 1-800-228-9290.
Mention IMAPS when booking
About the International Conference on High Temperature Electronics (HiTEC)

HiTEC 2020 continues the tradition of providing the leading biennial conference dedicated to the advancement and dissemination of knowledge of the high temperature electronics industry. HiTEC 2020 will be the forum for presenting leading high temperature electronics research results and application requirements. It will also be an opportunity to network with colleagues from around the world working to advance high temperature electronics.

Papers and exhibitors are anticipated from, but not limited to, the following areas:

<table>
<thead>
<tr>
<th>Applications:</th>
<th>Device Technologies:</th>
<th>MEMS and Sensors:</th>
<th>Packaging:</th>
</tr>
</thead>
<tbody>
<tr>
<td>- Geothermal</td>
<td>- Si, SOI</td>
<td>- Vibration</td>
<td>- Materials</td>
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<tr>
<td>- Oil well logging</td>
<td>- SiC</td>
<td>- Pressure</td>
<td>- Processing</td>
</tr>
<tr>
<td>- Automotive</td>
<td>- Diamond</td>
<td>- Seismic</td>
<td>- Solders/Brazes</td>
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<tr>
<td>- Military/aerospace</td>
<td>- GaN</td>
<td>- Etc.</td>
<td>- PC Boards</td>
</tr>
<tr>
<td>- Space</td>
<td>- GaAs</td>
<td></td>
<td>- Wire Bonding</td>
</tr>
<tr>
<td>- Etc.</td>
<td>- Contacts</td>
<td></td>
<td>- Flip Chip</td>
</tr>
<tr>
<td></td>
<td>- Dielectrics</td>
<td></td>
<td>- Insulation</td>
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<tr>
<td></td>
<td></td>
<td></td>
<td>- Thermal management</td>
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</tbody>
</table>

<table>
<thead>
<tr>
<th>Circuits:</th>
<th>Energy Sources:</th>
<th>Passives:</th>
<th>Reliability:</th>
</tr>
</thead>
<tbody>
<tr>
<td>- Analog</td>
<td>- Batteries</td>
<td>- Resistors</td>
<td>- Failure mechanisms</td>
</tr>
<tr>
<td>- Digital</td>
<td>- Nuclear</td>
<td>- Inductors</td>
<td>- Experimental and modeling results</td>
</tr>
<tr>
<td>- Power</td>
<td>- Fuel Cells</td>
<td>- Capacitors</td>
<td></td>
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<tr>
<td>- Wireless</td>
<td>- Etc.</td>
<td>- Oscillators</td>
<td></td>
</tr>
<tr>
<td>- Optical</td>
<td></td>
<td>- Connectors</td>
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www.imaps.org/hitec
About the 16th International Conference on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT)

The Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT) conference brings together a diverse set of disciplines to share experiences and promote opportunities to accelerate research, development and the application of ceramic interconnect and ceramic microsystems technologies. This international conference features ceramic technology for both microsystems and interconnect applications. Papers and exhibitors will be anticipated from, but not limited to, the following areas:

1. Functional materials for passive/active devices and their properties
   - Microwave/mm-wave LTCC/ULTCC dielectric materials
   - Ferroelectric/piezoelectric/pyroelectric/ferrite/multiferroic materials
   - Sensitive ceramics/thermoelectric/electrocaloric materials
   - Dielectric/ferroelectric/piezoelectric composites
   - Pastes/inks/slurries for electronics

2. Material processing and device manufacturing technologies
   - LTCC/HTCC and multilayer ceramic and glass processing
   - Emerging ultralow temperature, room temperature processing, and cold sintering processing
   - Additive manufacturing/3D printing/direct writing
   - Advanced thick film processing
   - Fine structuring technologies
   - Emerging embedding/integration technologies

3. Devices for emerging technologies
   - Circuits, antennas, and filters for MHz, GHz and THz for communications
   - Automotive/aerospace/medical electronics/optoelectronics
   - Flexible/wearable electronics
   - Integrated physical/chemical/biological sensors and actuators
   - Packaging and integration issues for MEMS and BioMEMS devices
   - Batteries/fuel cells/energy conversion systems
   - Micro-reactors/micro-fluidic devices

4. Design, modeling, simulation, characterization and reliability
   - Metamaterials design, realization and characterization
   - High frequency devices design/modeling/simulation
   - Materials and devices characterization
   - Material and device reliability, lifetime, and failure estimation
   - Thermal management/thermal transfer simulation

www.cicmt.org
About the International Conference on Thermal Management and Power Solutions

Presentations on leading-edge developments in thermal management components, materials, and systems solutions for effectively dissipating heat from microelectronic devices and systems are anticipated from industry and academia. The Workshop emphasizes practical, high-performance solutions that target current and evolving requirements in mobile, computing, telecom, power electronics, military, and aerospace systems. Papers and exhibitors will be anticipated from, but not limited to, the following areas:

• **Market Drivers:** Understanding thermal challenges and business/economic drivers that influence change in electronic systems design and manufacturing—and how these impact thermal design requirements. Developing market trends, market segmentation, cost drivers and reliability factors are examples of topics that set the framework for where and what types of new technical solutions are viable.

• **Multi-Die Packaging:** Advanced packaging technologies, such as System-In-Package, Multi-Chip Module and Multi-Package Module, stacked-die, etc. provide significant opportunities for miniaturization and performance enhancements. These technologies also can introduce significant thermal and interconnect challenges that must be balanced against those benefits.

• **Mobile and Handheld Devices and the Internet-of-Things (IoT):** Wearables, mobile and medical devices, small displays, tablets and notebooks are increasingly critical for our interconnected world. These devices often introduce unique component- and system-level thermal management challenges that require novel design approaches and materials.

• **Wireless and Telecom Infrastructure:** High performance telecom hardware have challenging component and system-level requirements that require technical advances to meet the evolving needs for routers, networked systems, base stations, etc.

• **Power Semiconductor Thermal Components, Systems, and Solutions:** Developments in IGBT thermal management and packaging strongly influence advances in electronic and electrical drive systems. These advances are increasingly important in the Electric Vehicle/Hybrid Electric Vehicle and renewable energy markets.

• **Military/Aerospace:** Emerging military and aerospace systems, including avionics, RF, and microwave components and modules for phased array radar, countermeasures, and other systems, require advanced thermal management as well as high-temperature materials and packaging.

• **System-Level Cooling:** The thermal design of complex systems, such as high-performance computing systems, relies on extensive component- and system-level thermal management analysis to address the broad spectrum of issues that entail a comprehensive system design.

• **Data Center Cooling:** Data center cooling includes a variety of design optimization activities including cooling provisioning, airflow control, temperature distribution and migration paths that range from forced air convection to system liquid cooling.

• **Liquid cooling, Phase-change, and Refrigeration:** Advanced cooling methods that use liquid, latent heat and/or active cooling provide opportunities for enhanced performance and design flexibility. Effective designs must balance these advantages against factors including life-cycle cost, reliability and serviceability impact.

• **Thermal Interface Materials (TIMs) and Testing:** Advanced thermal interface materials that may include organic, metallic, graphitic materials in bulk form as well as nanoscale are enabling significant advances in the thermal management of high-performance processors, memory, telecom, IGBT, RF, and microwave components and systems. Effective testing and reliability methods and standards are critical in determining the suitability of a TIM for a given application.

• **CTE-Matching and High Thermal Conductivity Materials:** Metallic, ceramic and composite materials have been engineered to exhibit excellent thermal conductivity with controlled coefficient of thermal expansion (CTE) properties to allow for better matching with GaN, SiC, silicon or ceramic materials to reduce thermal stresses in component packaging.

[www.imaps.org/thermal](http://www.imaps.org/thermal)
Come for one or come for all!

Each attendee registration includes joint access to all three conference programs, plus the networking and exhibit hall activities for one low price.

Each exhibitor registration includes a tabletop in the common networking hall and access to the common event registration list (3 times the reach of our traditional conferences!).

Sponsorship partners can choose from function sponsorships, single-conference sponsorships, or a premier multi-conference level of exposure. Each sponsorship includes a tabletop exhibit space in the common networking hall.
## Sponsorship and Exhibit Opportunities

<table>
<thead>
<tr>
<th>Type of Sponsorship</th>
<th>Description</th>
<th>Recognition</th>
<th>Extra Benefits</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>EVENT SPONSOR FOR</strong></td>
<td>Welcome reception -and- Conference lunches (two days)</td>
<td>Event webpage footer ad from March-April 2020</td>
<td>Leading logo exposure across the crossover webpage and all three conference webpages, marketing emails, final programs, and all applicable outlets</td>
</tr>
<tr>
<td><strong>HiTEC SPONSOR</strong></td>
<td>Conference breakfast in the joint networking hall (one day co-sponsorship)</td>
<td>Web ad on HiTEC event webpage, HiTEC final program full page ad, Recognition signage in HiTEC session room, Logo exposure on the HiTEC webpage, marketing emails, final program, and all applicable outlets</td>
<td>One tabletop exhibit space in joint networking hall, One (1) complimentary full event registration and one (1) exhibit personnel badge</td>
</tr>
<tr>
<td><strong>CICMT SPONSOR</strong></td>
<td>Conference breakfast in the joint networking hall (one day co-sponsorship)</td>
<td>Web ad on CICMT event webpage, CICMT final program full page ad, Recognition signage in CICMT session room, Logo exposure on the CICMT webpage, marketing emails, final program, and all applicable outlets</td>
<td>One tabletop exhibit space in joint networking hall, One (1) complimentary full event registration and one (1) exhibit personnel badge</td>
</tr>
<tr>
<td><strong>THERMAL SPONSOR</strong></td>
<td>Conference breakfast in the joint networking hall (one day co-sponsorship)</td>
<td>Web ad on Thermal event webpage, Thermal final program full page ad, Recognition signage in Thermal session room, Logo exposure on the Thermal webpage, marketing emails, final program, and all applicable outlets</td>
<td>One tabletop exhibit space in joint networking hall, One (1) complimentary full event registration and one (1) exhibit personnel badge</td>
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</table>

**HiTEC - CICMT - Thermal Management Cross Sponsorship and Exhibit Opportunities**

**COFFEE BREAK SPONSOR**

<table>
<thead>
<tr>
<th>Description</th>
<th>Recognition</th>
<th>Extra Benefits</th>
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<tbody>
<tr>
<td>One networking coffee break in the joint networking hall Choose from sole sponsorship of one coffee break or co-sponsorship (up to two sponsors)</td>
<td>Recognition signage during the coffee break</td>
<td>Logo exposure on the event webpages, marketing emails, final programs, and all applicable outlets</td>
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**TABLETOP EXHIBITOR**

<table>
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<tr>
<th>INCLUDES</th>
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<tbody>
<tr>
<td>One six-foot table with two chairs and access to electricity</td>
<td>One exhibit personnel badge</td>
</tr>
<tr>
<td>PDF attendee list (joint)</td>
<td></td>
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</tbody>
</table>

**RECOGNITION**

| Exhibitor listing in the final programs |

**EXTRA BENEFITS**

| Discounted full event registrations |

**Max**

- **3 available**
- **5 available**
- **10 available**
- **35 available**
HOW TO COMMIT TO A TABLETOP | Early Registration Discounts End April 8th

Exhibitor Details
Only 35 exhibitor spaces are available! These WILL sell out, so book early!

<table>
<thead>
<tr>
<th>Exhibitor Fees</th>
<th>Member</th>
<th>Non-Member</th>
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<tbody>
<tr>
<td>Early Registration</td>
<td></td>
<td></td>
</tr>
<tr>
<td><em>Booked on or before April 8th</em></td>
<td>$750</td>
<td>$850</td>
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<tr>
<td>Regular Registration</td>
<td></td>
<td></td>
</tr>
<tr>
<td><em>Booked after April 8th</em></td>
<td>$850</td>
<td>$950</td>
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</tbody>
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How to Register as an Exhibitor

1. Visit [www.imaps.org](http://www.imaps.org) and click to the Technology Crossover page to register for a tabletop space.
2. Log into an existing account. New to IMAPS? Create a visitor profile to complete registration.
3. Select the tabletop exhibition option on the registration page.
4. Complete payment.
5. IMAPS staff will contact you one to two weeks prior to the show to confirm shipping details, request badge details, and more.
HOW TO COMMIT TO A SPONSORSHIP

1. Contact Brian Schieman, Director of Programming and Technology, at bschieman@imaps.org with your sponsorship selection.
2. You will be provided with an invoice and instructions for payment.
3. Return payment along with a company logo file (for web and print use) and a URL for online linkage.
4. Ads are due to Brian Schieman by April 10th.
5. IMAPS staff will contact you one to two weeks prior to the show to confirm shipping details, request badge details, and more.

Don’t see what you want? All sponsorships can be customized to match your event exposure goals.

Premier Crossover Sponsor
$6,000

HiTEC Sponsor
$3,500

CICMT Sponsor
$3,500

Thermal Management Sponsor
$3,500

Coffee Break Sponsor
$2,500 or $1,500